

Mold-Tek Packaging Ltd to perform ground breaking ceremony for
new project | 1



Mold-Tek Packaging Ltd has scheduled a Ground Breaking Ceremony for its new plant building at TSIIIC, Patancheru Zone-General Park, IP-Sultanpur Sangareddy, Sy No.70 &174 Plot No.s G40/2, G41 & G4211 on Friday, December 10th, 2021.

The plant will be used to produce Injection Blow Moulded and Injection Moulded products for a variety of applications in the Food, FMCG, Pharma, Cosmetics and other segments.

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